

# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	-30	V
Gate-Source Voltage			V <sub>GSS</sub>	±25	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-12 -10	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = -10V	Steady State	$T_C = +25$ °C $T_C = +70$ °C	I <sub>D</sub>	-35 -25	А
Maximum Continuous Body Diode Forward Current (Note 7)			I <sub>S</sub>	-35	Α
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-80	Α
Pulsed Body Diode Forward Current (380µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	-80	Α
Avalanche Current (Note 8) L = 1mH			I <sub>AS</sub>	-14	Α
Avalanche Energy (Note 8) L = 1mH			E <sub>AS</sub>	100	mJ

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	P <sub>D</sub>	0.94	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>OJA</sub>	134	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	P <sub>D</sub>	1.94	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>OJA</sub>	65	°C/W
Total Power Dissipation (Note 7)		P <sub>D</sub>	31	W
Thermal Resistance, Junction to Case (Note 7)		R <sub>eJC</sub>	4.0	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

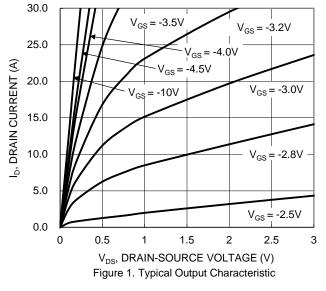
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1.0	_	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance		_	8	9.5	mΩ	$V_{GS} = -10V, I_D = -11.5A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	11	17		$V_{GS} = -4.5V$ , $I_{D} = -8.5A$	
Diode Forward Voltage	V <sub>SD</sub>	_	-0.7	-1.2	V	$V_{GS} = 0V, I_{S} = -1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>	_	1674	_	pF	45)/ )/ 0)/	
Output Capacitance	Coss	_	302	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	230	_	pF		
Gate Resistance	Rg	_	15.2	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -5V)	Qg	_	16.2	_	nC		
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	33.7	_	nC	V <sub>DS</sub> = -15V, I <sub>D</sub> = -11.5A	
Gate-Source Charge	Q <sub>qs</sub>	_	3.5	_	nC		
Gate-Drain Charge	Q <sub>gd</sub>	_	6.7	_	nC		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.0	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	4.5	_	ns	$V_{DD} = -15V$ , $V_{GS} = -10V$ , $R_G = 6\Omega$ , $I_D = -11.5A$	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	96	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	106.5	_	ns		
Reverse Recovery Time	t <sub>RR</sub>	_	46	_	ns	I <sub>S</sub> = -11.5A, dI/dt = 100A/μs	
Reverse Recovery Charge	$Q_{RR}$	_	25.5	_	nC		

Notes: 5. De

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.
- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.





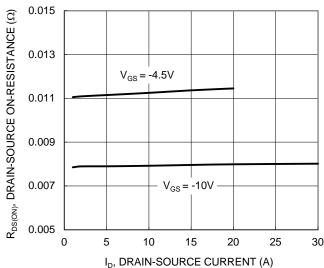


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

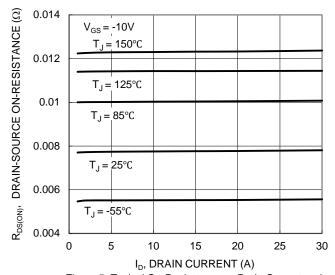
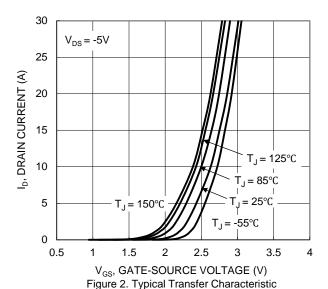


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



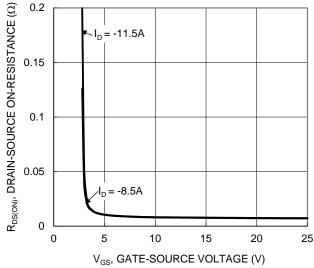
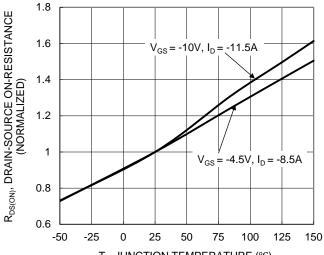


Figure 4. Typical Transfer Characteristic



T<sub>J</sub>, JUNCTION TEMPERATURE (°C)
Figure 6. On-Resistance Variation with Junction
Temperature



30

25

20

15

10

5

0

0

T<sub>A</sub>= 125℃

0.6

T<sub>A</sub>= 150°C

0.3

4<sub>S</sub>, SOURCE CURRENT (A)

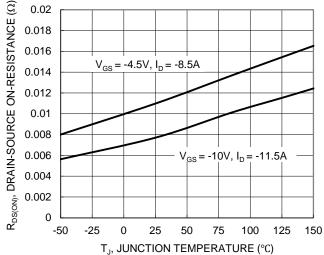
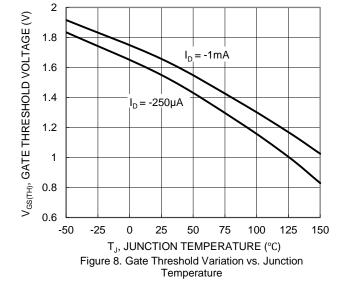
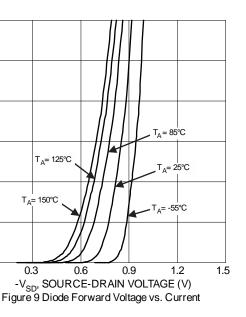


Figure 7. On-Resistance Variation with Junction Temperature





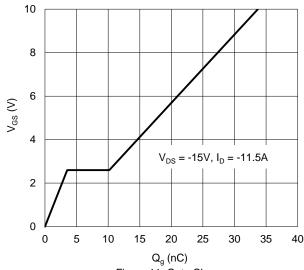
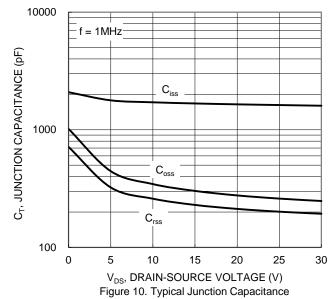


Figure 11. Gate Charge



100 100µs R<sub>DS(ON)</sub> Limited DRAIN CURRENT (A) 10 1  $P_W = 10 ms$ P<sub>W</sub> = 100ms <u>م</u> 0.1  $T_{J(Max)} = 150$  °C  $T_C = 25$  °C Single Pulse  $P_W = 10s$ DUT on 1\*MRP Board DC  $V_{GS} = -10V$ 0.01 0.01 10 100 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V)



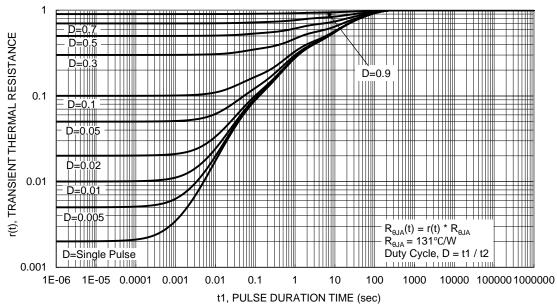


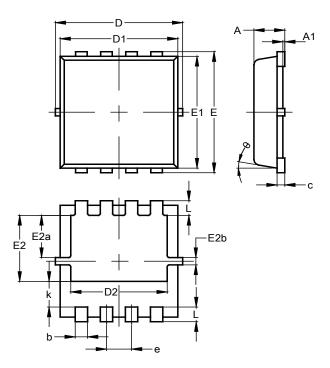
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### PowerDI3333-8 (Type UX)

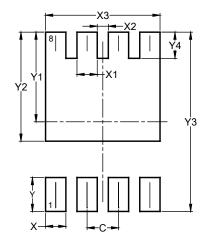


PowerDI3333-8 (Type UX)					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05			
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	2.30	2.70	2.50		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E2a	0.95	1.35	1.15		
E2b	0.10	0.30	0.20		
е	0.65 BSC				
k	0.50	0.90	0.70		
L	0.30	0.50	0.40		
θ	0°	12°	10°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## PowerDI3333-8 (Type UX)



Dimensions	Value (in mm)
С	0.650
Х	0.420
X1	0.420
X2	0.230
Х3	2.370
Υ	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540



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